Winstar Display Co., LTD
華凌光電股份有限公司
住址: 407 台中市中清路 163 號
No.163 Chung Ching RD.,
Taichune, Taiwan, R.O.C
WEB: http://www.winstar.com.tw
E-mail: sales@winstar.com.tw
Tel:886-4-24262208 Fax：886-4-24262207

SPECIFICATION

CUSTOMER : _____

MODULE NO.: WF57DTIBCDC#

APPROVED BY: (FOR CUSTOMER USE ONLY)	**PCB VERSION:** **DATA:**

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2009/5/15		First issue

Winstar Display Co., LTD
華凌光電股份有限公司

MODLE NO：

DOC. FIRST ISSUE

RECORDS OF REVISION

VERSION	DATE	REVISED PAGE NO.	**SUMMARY**
0	2009/5/15		First issue

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1.Module Classification Information

W F 57 D T I B C D C #
① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨⑩ ⑪

① Brand：WINSTAR DISPLAY CORPORATION
② Display Type：H→Character Type, G→Graphic Type F→TFT Type
③ Display Size：5.7” TFT
④ Model serials no.
⑤ Backlight Type： F→CCFL, White T→LED, White

⑥ LCD Polarize Type/ Temperature range/ View direction

A→Reflective, N.T, 6:00	H→Transflective, W.T,6:00
D→Reflective, N.T, 12:00	K→Transflective, W.T,12:00
G→Reflective, W. T, 6:00	C→Transmissive, N.T,6:00
J→Reflective, W. T, 12:00	F→Transmissive, N.T,12:00
B→Transflective, N.T,6:00	I→Transmissive, W. T, 6:00
E→Transflective, N.T.12:00	L→Transmissive, W.T,12:00

⑦ A: TFT LCD
B: TFT+FR+CONTROL BOARD
C: TFT+FR+A/D BOARD
D:TFT+FR+A/D BOARD+CONTROL BOARD

⑧ Solution: A: 128160 B:320234 C:320240 D:480234

⑨ D: Digital A: Analog

⑩ Version

⑪ Special Code #:Fit in with ROHS directive regulations

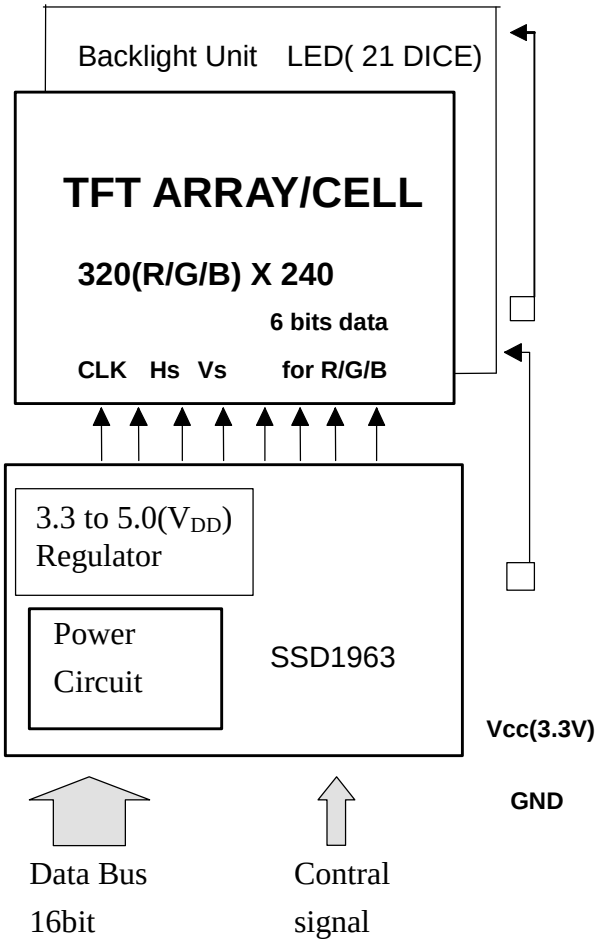
This product is composed of a TFT LCD panel, driver ICs, FPC, Control Board and a backlight unit. The following table described the features of WF57DTIBCDC#

Item	Dimension	Unit
Dot Matrix	320 x RGBx240(TFT)	dots
Module dimension	126.0x 101.55 x 5.8 (max)	mm
View area	117.9x 89.1	mm
Dot pitch	0.12 x 0.36	mm
Driving IC package	COG	
LCD type	TFT, Negative, Transmissive	
View direction	6 o'clock	
Backlight Type	LED,Normally White	
Controller IC	SSD1963	

*Expose the IC number blaze (Luminosity over than 1 cd) when using the LCM may cause IC operating failure.

*Color tone slight changed by temperature and driving voltage.

2.Block Diagram (8BITS Mode)



3.Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	VCC	—	3.0	3.3	3.6	V
Input High Volt.	V_{IH}	—	0.8VDDIO	—	VDDIO + 0.5	V
Input Low Volt.	V_{IL}	—	—	—	0.2VDDIO	V
LCD Driving Supply Voltage	V_{GH}*1	Ta=25℃		15		V *3
	V_{GL}*2			-10		V
	Vcom		—	3.7	—	
Supply Current	I_{VDD}	V_{DD}=3.3V	—	121	—	mA

Notes:
*1) VGH is TFT Gate on operating Voltage.
*2) VGL is TFT Gate off operating Voltage, VGL signal must be fluctuates with same phase as Vcom when Storage on Gate structure.
*3) Vcom must be adjusted to optimize display quality_Crosstalk,Contrast Ratio and etc.

4.Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	℃
Storage Temperature	T_{ST}	-30	—	+80	℃
Power Supply Voltage	V_{GH}	-0.3	—	18	V
	V_{GL}	-15	—	0.3	V
	VCC	-0.3	—	6.0	V

5.Interface Pin Function

5-1 Pins Connection To Control Board

P/N	Symbol	16BIT Function	P/N	Symbol	16BIT Function
1	GND	Ground	26	RST	Reset
2	VCC	Power supply for Logic	27	RL	Scan direction
3	NC	No connection	28	UD	Scan direction
4	RS		29	NC	No connection
5	WR	8080 family MPU interface : Write signal	30	NC	No connection
6	RD	8080 family MPU interface: Read signal	31	NC	No connection
7	DB0	Data bus	32	NC	No connection
8	DB1				
9	DB2				
10	DB3				
11	DB4				
12	DB5				
13	DB6				
14	DB7				
15	DB8				
16	DB9				
17	DB10				
18	DB11				
19	DB12				
20	DB13				
21	DB14				
22	DB15				
23	NC	No connection			
24	NC	No connection			
25	CS	Chip select			

6. DC CHARATERISTICS

Conditions:
Voltage referenced to VSS
VDDD, VDDPLL = 1.2V
VDDIO, VDDLCD = 3.3V
TA = 25°C

DC Characteristics

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
PSTY	Quiescent Power			300		uW
IIZ	Input leakage current		-1		1	uA
IOZ	Output leakage current		-1		1	uA
VOH	Output high voltage		0.8VDDIO			V
VOL	Output low voltage				0.2VDDIO	V
VIH	Input high voltage		0.8VDDIO		VDDIO + 0.5	V
VIL	Input low voltage				0.2VDDIO	V

7. AC Characteristics

Conditions:
Voltage referenced to V_{SS}
V_{DDD}, V_{DDPLL} = 1.2V
V_{DDIO}, V_{DDLCD} = 3.3V
T_A = 25°C
C_L = 50pF (Bus/CPU Interface)
C_L = 0pF (LCD Panel Interface)

7.1Clock Timing

Clock Input Requirements for CLK (PLL-bypass)

Symbol	Parameter	Min	Max	Units
FCLK	Input Clock Frequency (CLK)		120	MHz
TCLK	Input Clock period (CLK)	1/fCLK		ns

Clock Input Requirements for CLK (Using PLL)

Symbol	Parameter	Min	Max	Units
FCLK	Input Clock Frequency (CLK)	2.5	50	MHz
TCLK	Input Clock period (CLK)	1/fCLK		ns

Clock Input Requirements for crystal oscillator XTAL (Using PLL)

Symbol	Parameter	Min	Max	Units
FXTAL	Input Clock Frequency	2.5	10	MHz
TXTAL	Input Clock period	1/fXTAL		ns

7.2 MCU Interface Timing

7.2.1 6800 Mode

Table 7-4: 6800 Mode Timing

Symbol	Parameter	Min	Typ	Max	Unit
tcyc	Reference Clock Cycle Time	9	-	-	ns
tPWCSL	Pulse width CS# or E low	1	-	-	tCYC
tPWCSH	Pulse width CS# or E high	1	-	-	tCYC
tFDRD	First Data Read Delay	5	-	-	tCYC
tAS	Address Setup Time	1	-	-	ns
tAH	Address Hold Time	1	-	-	ns
tDSW	Data Setup Time	4	-	-	ns
tDHW	Data Hold Time	1	-	-	ns
tDSR	Data Access Time	-	-	5	ns
tDHR	Output Hold time	1	-	-	ns

Figure 7-1: 6800 Mode Timing Diagram (Use CS# as Clock)

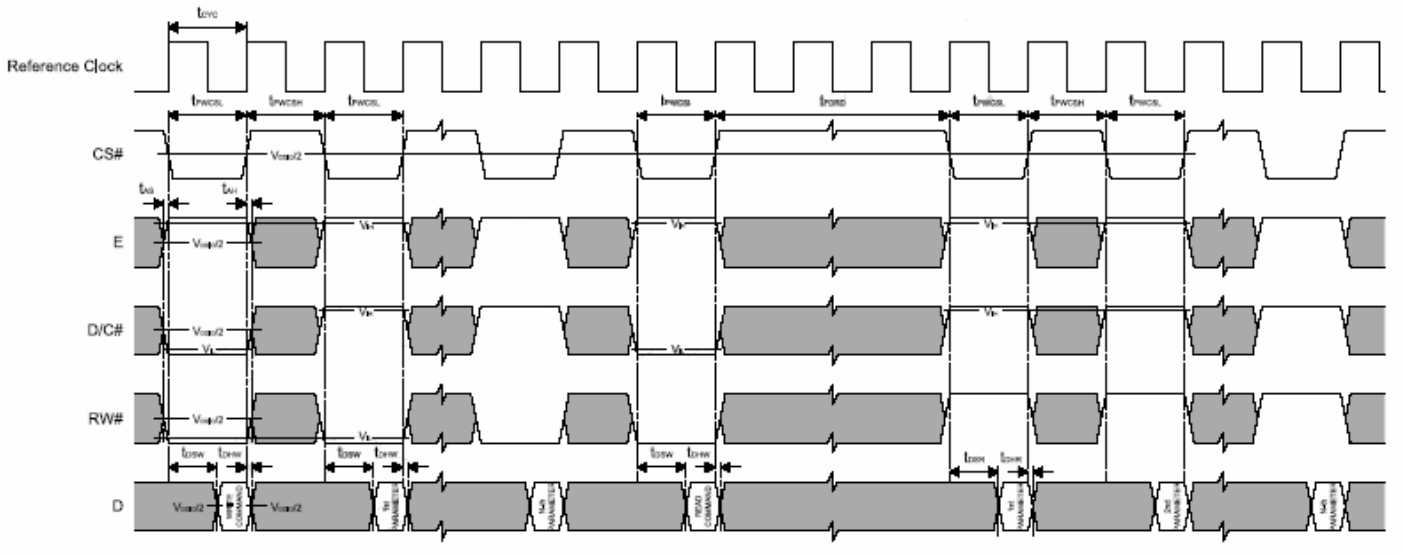
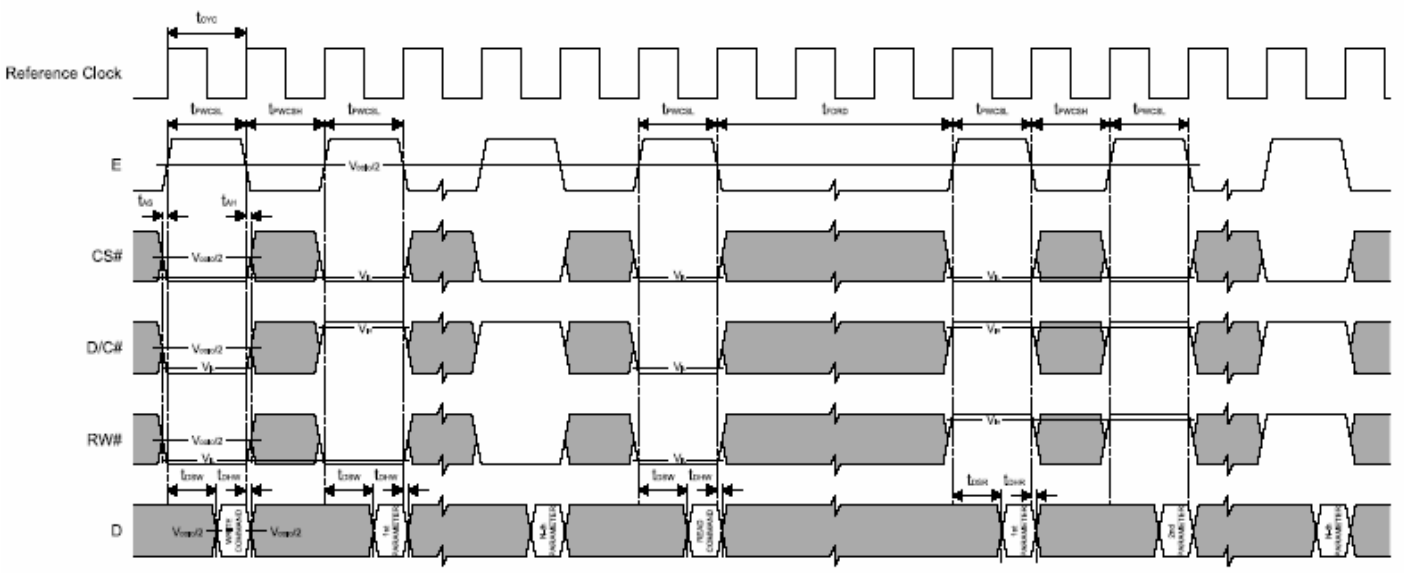


Figure 7-2: 6800 Mode Timing Diagram (Use E as Clock)

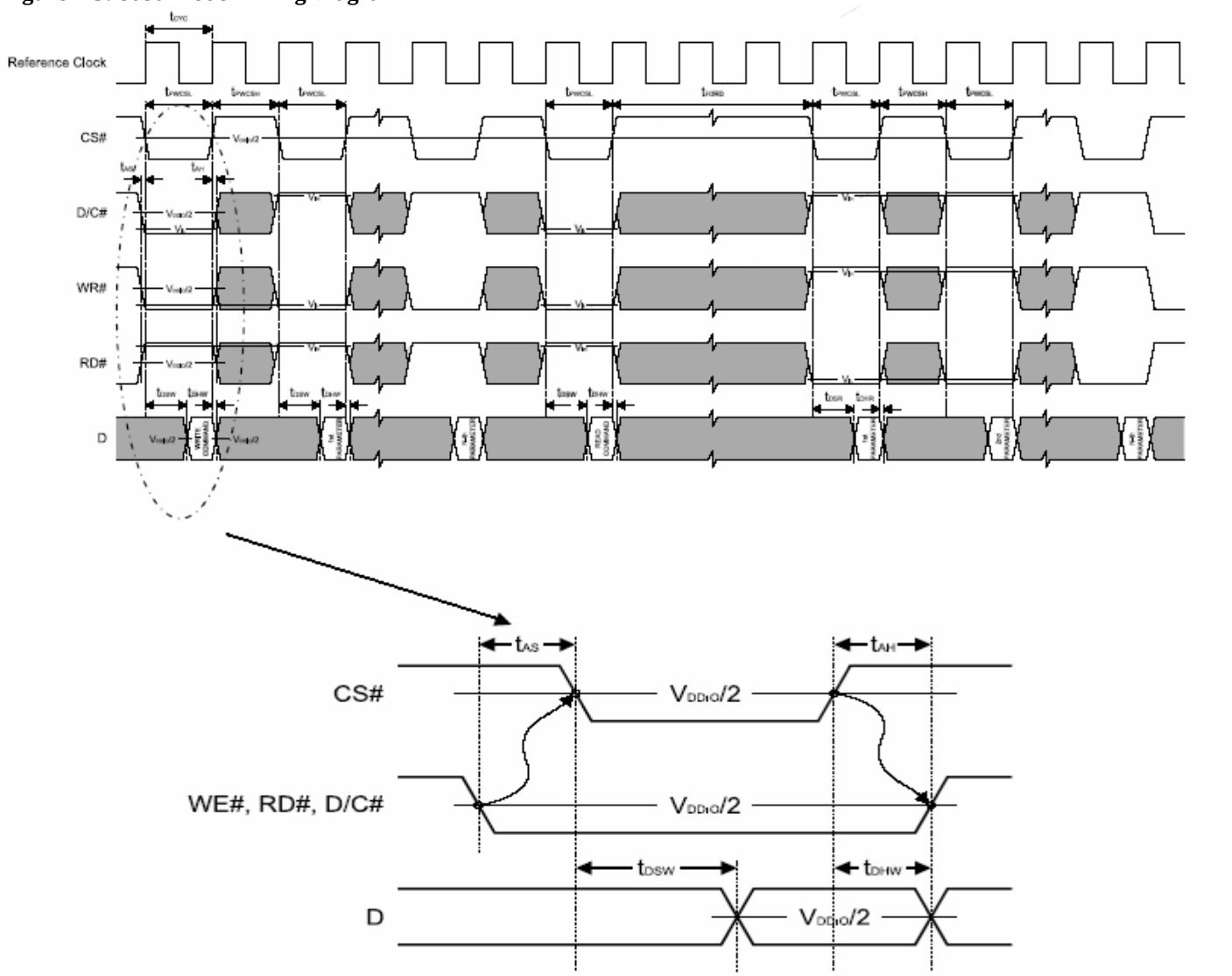


7.2.2 8080 Mode Write Cycle

Table 7-5: 8080 Mode Timing

Symbol	Parameter	Min	Typ	Max	Unit
tcyc	Reference Clock Cycle Time	9	-	-	ns
tPWCSL	Pulse width CS# low	1	-	-	tCYC
tPWCSH	Pulse width CS# high	1	-	-	tCYC
tFDRD	First Read Data Delay	5	-	-	tCYC
tAS	Address Setup Time	1	-	-	ns
tAH	Address Hold Time	1	-	-	ns
tDSW	Data Setup Time	4	-	-	ns
tDHW	Data Hold Time	1	-	-	ns
tDSR	Data Access Time	-	-	5	ns
tDHR	Output Hold time	1	-	-	ns

Figure 7-3: 8080 Mode Timing Diagram



8. Data transfer order Setting

Pixel Data Format

Both 6800 and 8080 support 8-bit, 9-bit, 16-bit, 18-bit and 24-bit data bus. Depending on the width of the data bus, the display data are packed into the data bus in different ways.

Pixel Data Format：

Interface	Cycle	D[23]	D[22]	D[21]	D[20]	D[19]	D[18]	D[17]	D[16]	D[15]	D[14]	D[13]	D[12]	D[11]	D[10]	D[9]	D[8]	D[7]	D[6]	D[5]	D[4]	D[3]	D[2]	D[1]	D[0]
24 bits	1st	R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0
18 bits	1st							R5	R4	R3	R2	R1	R0	G5	G4	G3	G2	G1	G0	B5	B4	B3	B2	B1	B0
16 bits (565 format)	1st									R5	R4	R3	R2	R1	G5	G4	G3	G2	G1	G0	B5	B4	B3	B2	B1
16 bits	1st									R5	R4	R3	R2	R1	R0	X	X	G5	G4	G3	G2	G1	G0	X	X
	2nd									B5	B4	B3	B2	B1	B0	X	X	R5	R4	R3	R2	R1	R0	X	X
	3rd									G5	G4	G3	G2	G1	G0	X	X	B5	B4	B3	B2	B1	B0	X	X
9 bits	1st																R5	R4	R3	R2	R1	R0	G5	G4	G3
	2nd																G2	G1	G0	B5	B4	B3	B2	B1	B0
8 bits	1st																	R5	R4	R3	R2	R1	R0	X	X
	2nd																	G5	G4	G3	G2	G1	G0	X	X
	3rd																	B5	B4	B3	B2	B1	B0	X	X

X: Don't Care

9 Register Depiction

Please consult the spec of SSD1963

10. OPTICAL CHARATERISTIC

Ta=25±2℃, ILED=20mA

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response time		Tr	θ =0° 、 Φ=0°	-	10		ms	Note 3,5
		Tf		-	15		ms	
Contrast ratio		CR	At optimized viewing angle	300	400	-	-	Note 4,5
Color Chromaticity	White	Wx	θ =0° 、 Φ=0	(0.26)	(0.31)	(0.36)		Note 2,6,7
		Wy		(0.28)	(0.33)	(0.38)		
	Red	Rx	θ =0° 、 Φ=0					
		Ry						
	Green	Gx	θ =0° 、 Φ=0					
		Gy						
	Blue	Bx	θ =0° 、 Φ=0					
		By						
Viewing angle	Hor.	ΘR	CR≧10	(50)	(60)		Deg.	Note 1
		ΘL		(50)	(60)			
	Ver.	ΦT		(40)	(50)			
		ΦB		(45)	(55)			
Brightness		-	-	200	250	-	cd/m^2	Center of display

Ta=25±2℃, I_L=20mA

Note 1: Definition of viewing angle range

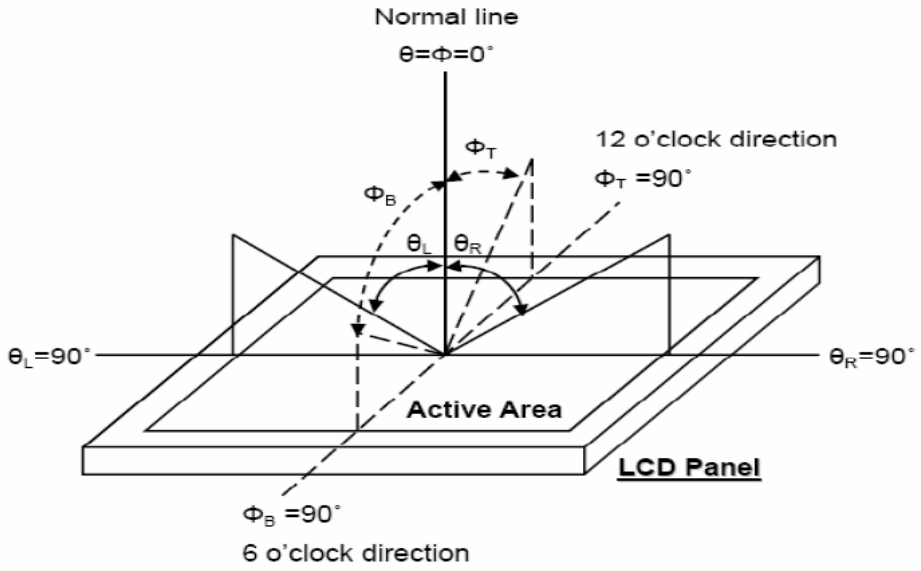


Fig. 8-1 Definition of viewing angle

Note 2: Test equipment setup:

After stabilizing and leaving the panel alone at a driven temperature for 10 minutes, the measurement should be executed. Measurement should be executed in a stable, windless, and dark room. Optical specifications are measured by Topcon BM-7 luminance meter 1.0° field of view at a distance of 50cm and normal direction.

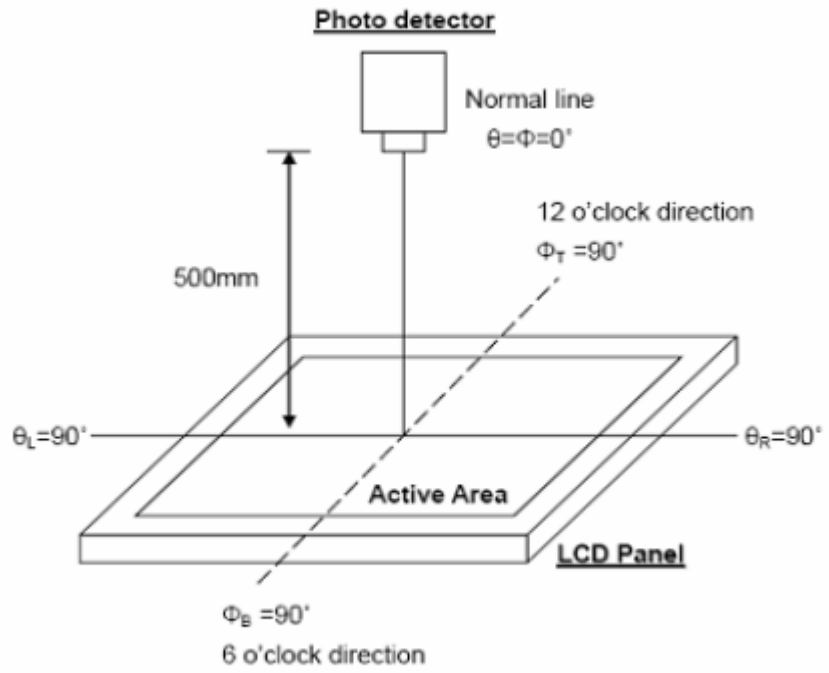


Fig. 8-2 Optical measurement system setup

Note 3: Definition of Response time:
The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time, Tr, is the time between photo detector output intensity changed from 90% to 10% . And fall time, Tf, is the time between photo detector output intensity changed from10% to 90% .

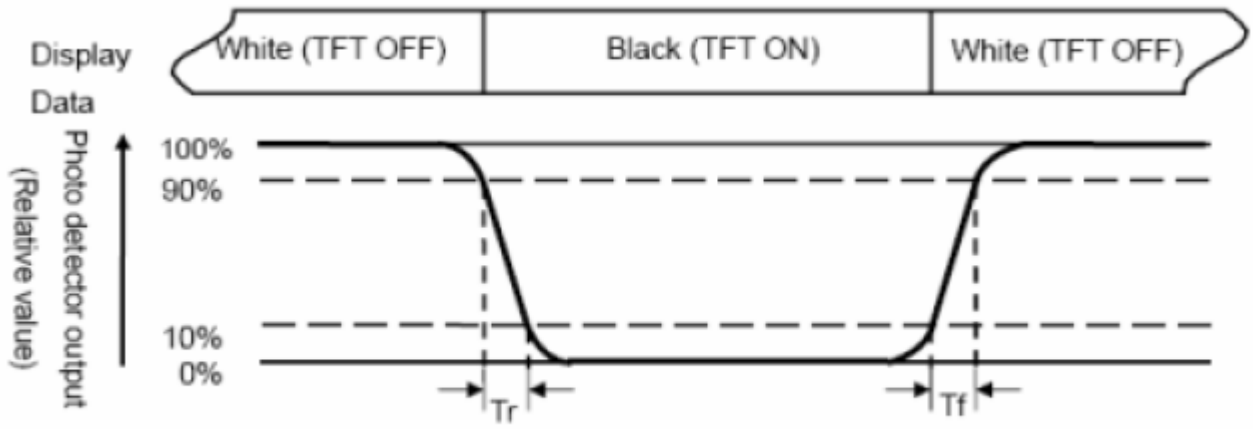


Fig. 3-3 Definition of response time

Note 4: Definition of contrast ratio:
The contrast ratio is defined as the following expression.

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD on the "White" state}}{\text{Luminance measured when LCD on the "Black" state}}$$

Note 5: White Vi = Vi50 ± 1.5V
Black Vi = Vi50 ± 2.0V
"±" means that the analog input signal swings in phase with VCOM signal.
"±" means that the analog input signal swings out of phase with VCOM signal.
The 100% transmission is defined as the transmission of LCD panel when all the input terminals of

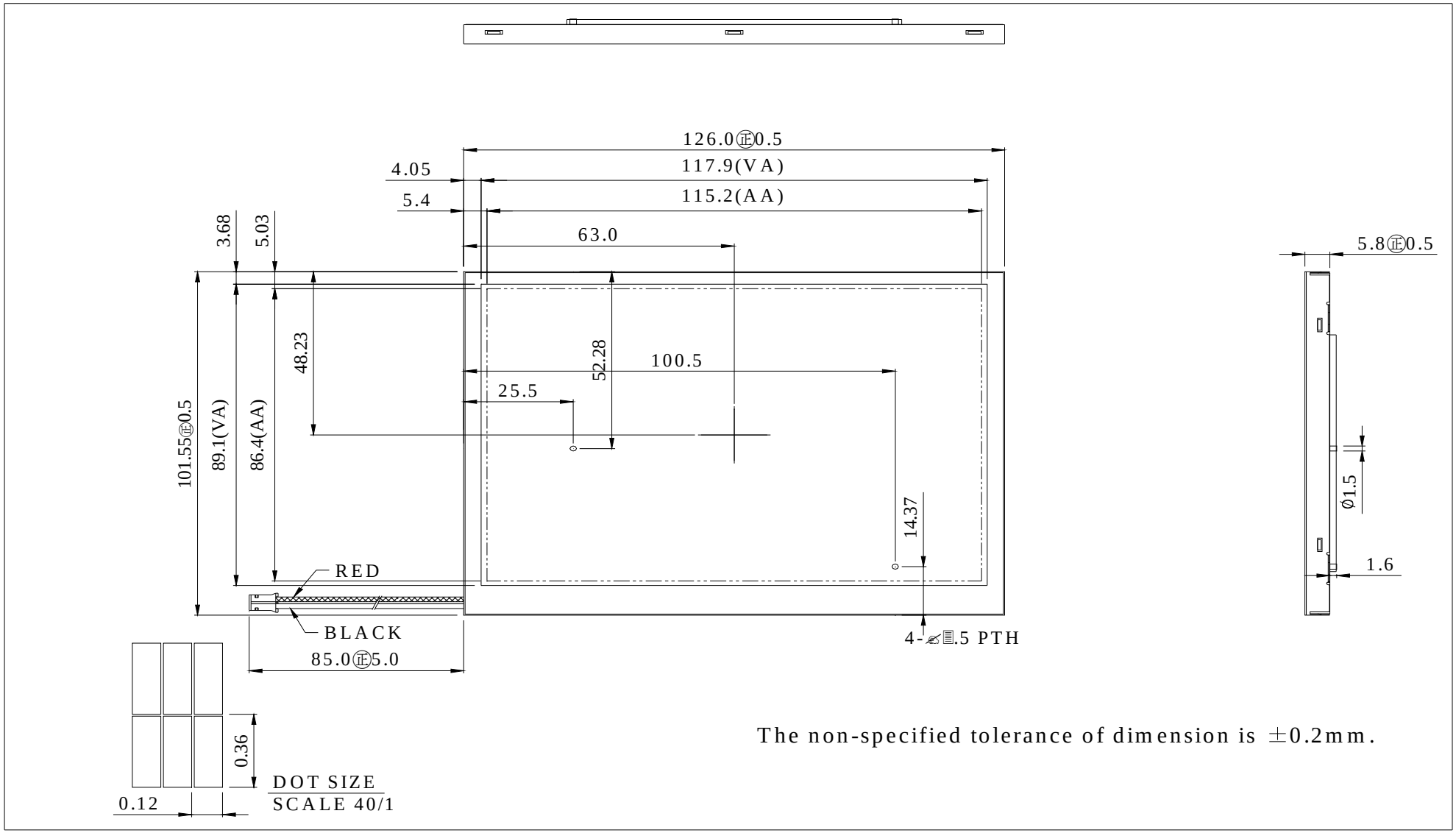
module are electrically opened.

Note 6: Definition of color chromaticity (CIE 1931)
Color coordinates measured at the center point of LCD

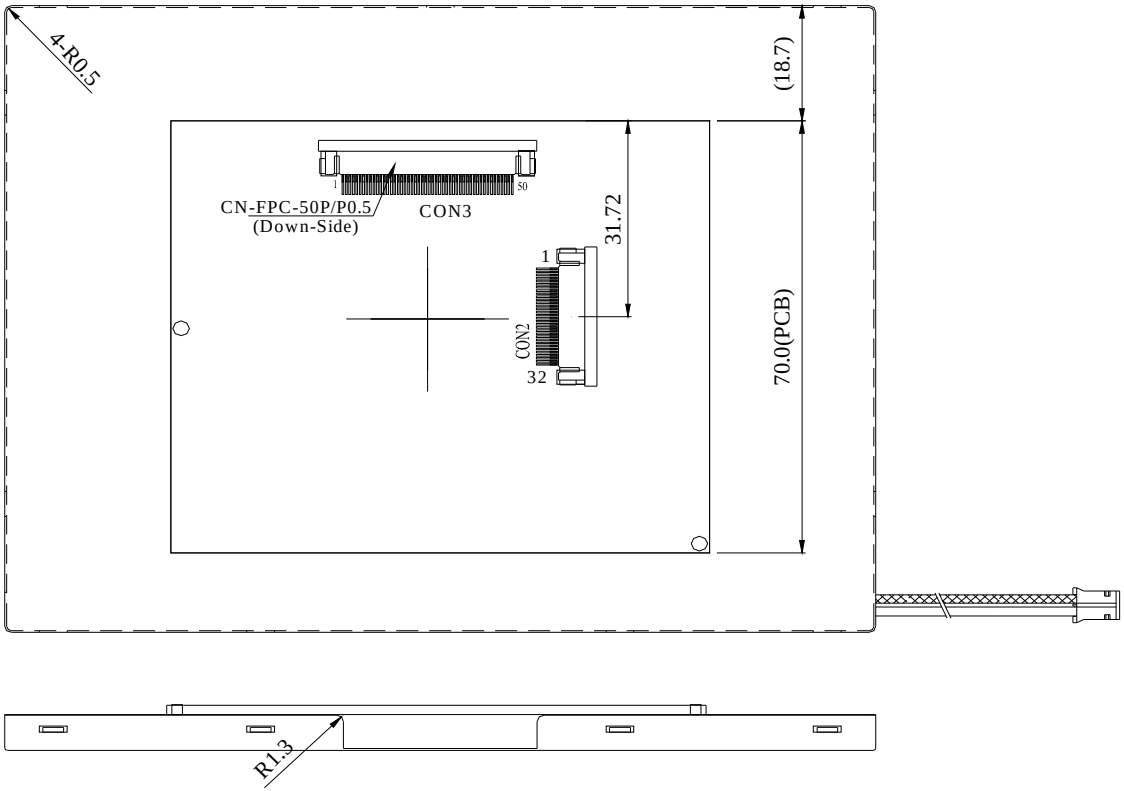
Note 7: Measured at the center area of the panel when all the input terminals of LCD panel are electrically opened.

$$\text{Note 8 : Uniformity (U)} = \frac{\text{Brightness (min)}}{\text{Brightness (max)}} \times 100\%$$

11.Contour Drawing



CON2



16bit mode

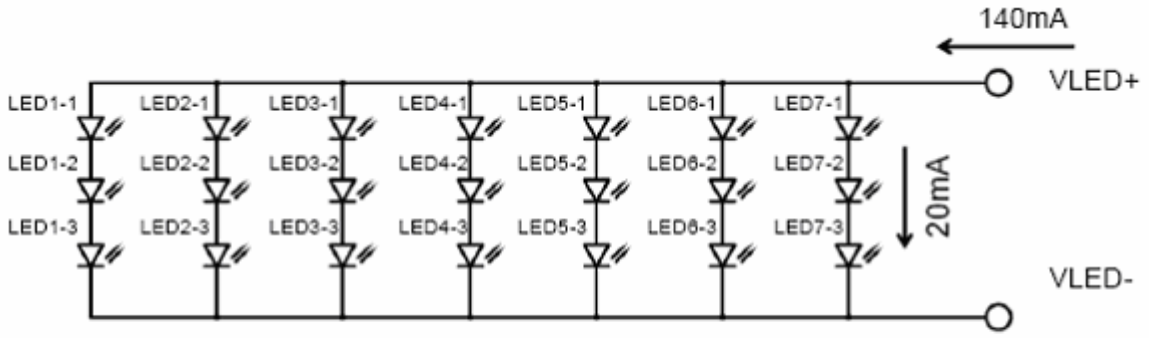
PIN NO.	SYMBOL	PIN NO.	SYMBOL
1	GND	18	DB11
2	VCC	19	DB12
3	NC	20	DB13
4	RS	21	DB14
5	WR	22	DB15
6	RD	23	NC
7	DB0	24	NC
8	DB1	25	CS
9	DB2	26	RST
10	DB3	27	RL
11	DB4	28	UD
12	DB5	29	NC
13	DB6	30	NC
14	DB7	31	NC
15	DB8	32	NC
16	DB9		
17	DB10		

The non-specified tolerance of dimension is ±0.2mm.

12. LED driving conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit	Remark
LED Current	I_{LED}	----	140	210	mA	Note1
LED voltage	V_{LED}	9.0	10.2	10.5	V	
LED life Time	-	(10,000)	----	----	-	Note 2,3
Luminous Intensity	IV	----	300	----	CD/M^2	Note 4

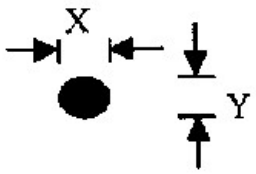
Note 1: There are 7 Groups LED shown as below, =9.9 V(Min)

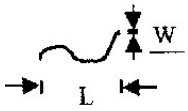


Note 2 : Ta = 25℃ ,
Note 3 : Brightess to be decreased to 50% of the initial value.

Note 4: The luminous is measured through LCD panel.

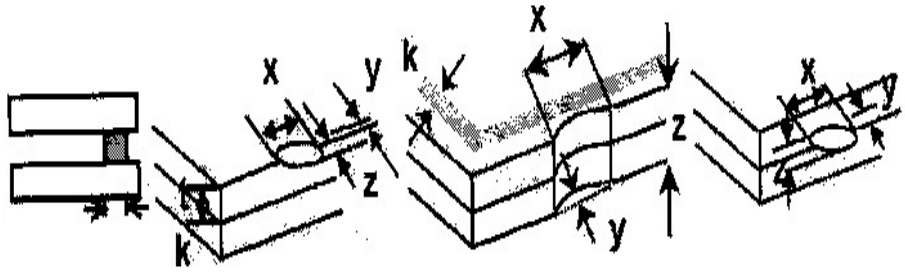
13. Inspection specification

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>01</td><td>Electrical Testing</td><td>1.1 Missing vertical, horizontal segment, segment contrast defect.
1.2 Missing character , dot or icon.
1.3 Display malfunction.
1.4 No function or no display.
1.5 Current consumption exceeds product specifications.
1.6 LCD viewing angle defect.
1.7 Mixed product types.
1.8 Contrast defect.</td><td>0.65</td></tr>
<tr><td>02</td><td>Black or white spots on LCD (display only)</td><td>2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present.
2.2 Densely spaced: No more than two spots or lines within 3mm</td><td>2.5</td></tr>
<tr><td rowspan="2">03</td><td rowspan="2">LCD black spots, white spots, contamination (non-display)</td><td>3.1 Round type : As following drawing
Φ=(x + y) / 2
 

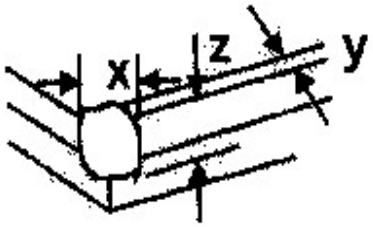
<table>
<tr><th>SIZE</th><th>Acceptable Q TY</th></tr>
<tr><td>Φ ≦0.10</td><td>Accept no dense</td></tr>
<tr><td>0.10＜Φ ≦0.20</td><td>2</td></tr>
<tr><td>0.20＜Φ ≦0.25</td><td>1</td></tr>
<tr><td>0.25＜Φ</td><td>0</td></tr>
</table></td><td>2.5</td></tr>
<tr><td>3.2 Line type : (As following drawing)
 

<table>
<tr><th>Length</th><th>Width</th><th>Acceptable Q TY</th></tr>
<tr><td>---</td><td>W≦0.02</td><td>Accept no dense</td></tr>
<tr><td>L≦3.0</td><td>0.02＜W≦0.03</td><td rowspan="2">2</td></tr>
<tr><td>L≦2.5</td><td>0.03＜W≦0.05</td></tr>
<tr><td>---</td><td>0.05＜W</td><td>As round type</td></tr>
</table></td><td>2.5</td></tr>
<tr><td>04</td><td>Polarizer bubbles</td><td>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.
<table>
<tr><th>Size Φ</th><th>Acceptable Q TY</th></tr>
<tr><td>Φ ≦0.20</td><td>Accept no dense</td></tr>
<tr><td>0.20＜Φ ≦0.50</td><td>3</td></tr>
<tr><td>0.50＜Φ ≦1.00</td><td>2</td></tr>
<tr><td>1.00＜Φ</td><td>0</td></tr>
<tr><td>Total Q TY</td><td>3</td></tr>
</table></td><td>2.5</td></tr>
</table>

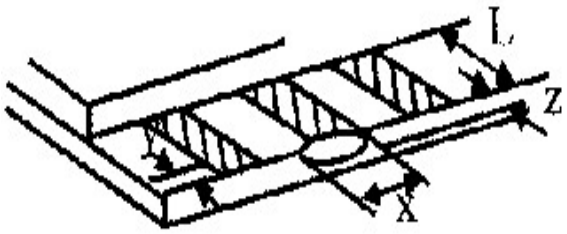
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>05</td><td>Scratches</td><td>Follow NO.3 LCD black spots, white spots, contamination</td><td></td></tr>
<tr><td>06</td><td>Chipped glass</td><td>
Symbols Define:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length:

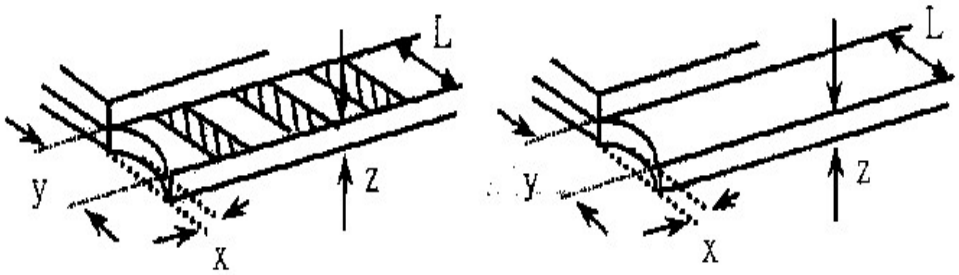
6.1 General glass chip :
6.1.1 Chip on panel surface and crack between panels:


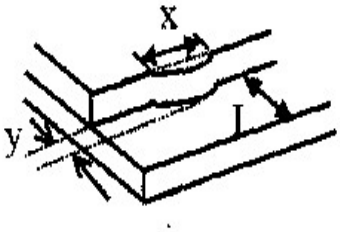
<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>
⊙If there are 2 or more chips, x is total length of each chip.

6.1.2 Corner crack:


<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>
⊙If there are 2 or more chips, x is the total length of each chip.
</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>06</td><td>Glass crack</td><td>
Symbols :
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
6.2 Protrusion over terminal :
6.2.1 Chip on electrode pad :


<table>
<tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr>
<tr><td>y≦0.5mm</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>
6.2.2 Non-conductive portion:


<table>
<tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr>
<tr><td>y≦ L</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>
⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
⊙If the product will be heat sealed by the customer, the alignment mark not be damaged.
6.2.3 Substrate protuberance and internal crack.


<table>
<tr><td>y: width</td><td>x: length</td></tr>
<tr><td>y≦1/3L</td><td>x ≦ a</td></tr>
</table>
</td><td>2.5</td></tr>
</table>

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn’ t light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

winstar **LCM Sample Estimate Feedback Sheet**

Module Number： _____ **Page: 1**

1、Panel Specification：

1. Panel Type： ☐ Pass ☐ NG ,_____
2. View Direction： ☐ Pass ☐ NG ,_____
3. Numbers of Dots： ☐ Pass ☐ NG ,_____
4. View Area： ☐ Pass ☐ NG ,_____
5. Active Area： ☐ Pass ☐ NG ,_____
6. Operating Temperature： ☐ Pass ☐ NG ,_____
7. Storage Temperature： ☐ Pass ☐ NG ,_____
8. Others：_____

2、Mechanical Specification：

1. PCB Size： ☐ Pass ☐ NG ,_____
2. Frame Size： ☐ Pass ☐ NG ,_____
3. Material of Frame： ☐ Pass ☐ NG ,_____
4. Connector Position： ☐ Pass ☐ NG ,_____
5. Fix Hole Position： ☐ Pass ☐ NG ,_____
6. Backlight Position： ☐ Pass ☐ NG ,_____
7. Thickness of PCB： ☐ Pass ☐ NG ,_____
8. Height of Frame to PCB： ☐ Pass ☐ NG ,_____
9. Height of Module： ☐ Pass ☐ NG ,_____
10. Others： ☐ Pass ☐ NG ,_____

3、Relative Hole Size：

1. Pitch of Connector： ☐ Pass ☐ NG ,_____
2. Hole size of Connector： ☐ Pass ☐ NG ,_____
3. Mounting Hole size： ☐ Pass ☐ NG ,_____
4. Mounting Hole Type： ☐ Pass ☐ NG ,_____
5. Others： ☐ Pass ☐ NG ,_____

4、Backlight Specification：

1. B/L Type： ☐ Pass ☐ NG ,_____
2. B/L Color： ☐ Pass ☐ NG ,_____
3. B/L Driving Voltage (Reference for LED Type)： ☐ Pass ☐ NG ,_____
4. B/L Driving Current： ☐ Pass ☐ NG ,_____
5. Brightness of B/L： ☐ Pass ☐ NG ,_____
6. B/L Solder Method： ☐ Pass ☐ NG ,_____
7. Others： ☐ Pass ☐ NG ,_____

＞＞ Go to page 2 ＜＜

5、Electronic Characteristics of Module：

1.	Input Voltage：	☐ Pass	☐ NG , _____
2.	Supply Current：	☐ Pass	☐ NG , _____
3.	Driving Voltage for LCD：	☐ Pass	☐ NG , _____
4.	Contrast for LCD：	☐ Pass	☐ NG , _____
5.	B/L Driving Method：	☐ Pass	☐ NG , _____
6.	Negative Voltage Output：	☐ Pass	☐ NG , _____
7.	Interface Function：	☐ Pass	☐ NG , _____
8.	LCD Uniformity：	☐ Pass	☐ NG , _____
9.	ESD test：	☐ Pass	☐ NG , _____
10.	Others：	☐ Pass	☐ NG , _____

6、Summary：

Sales signature： _____

Customer Signature： _____ **Date：** ____ / ____ / ____